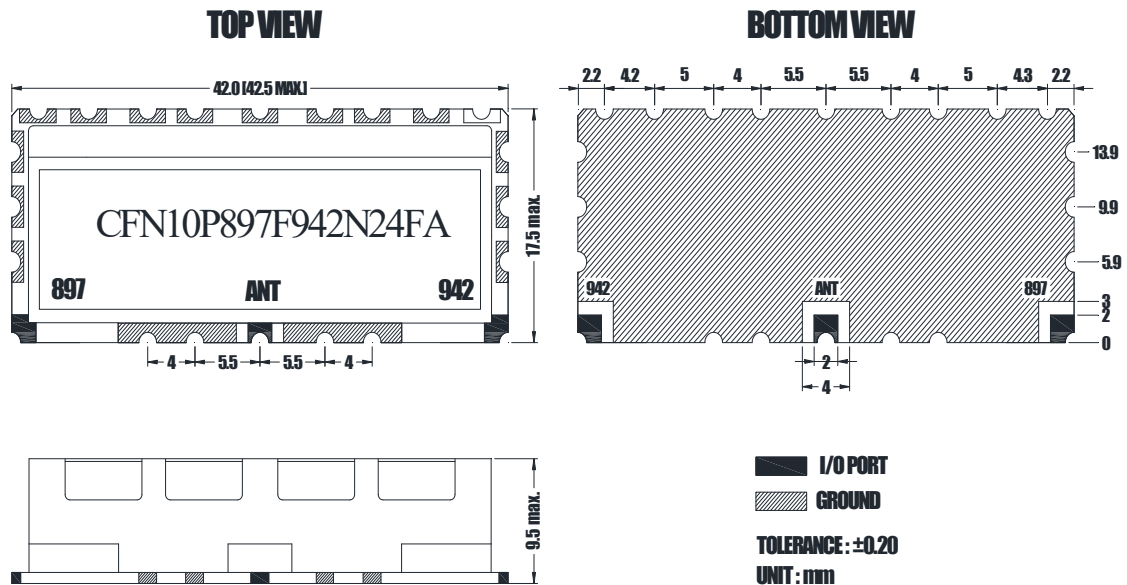


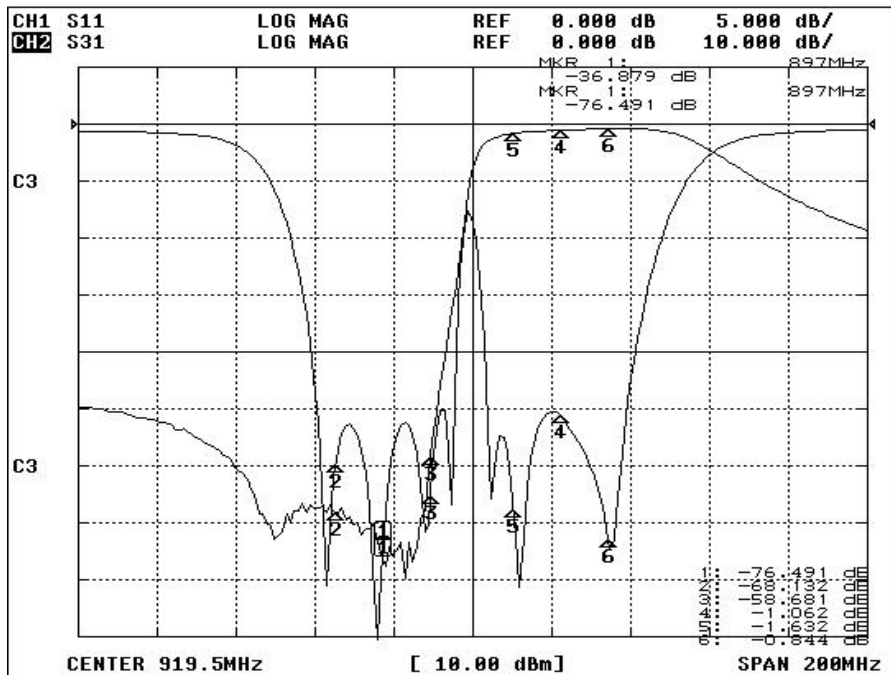
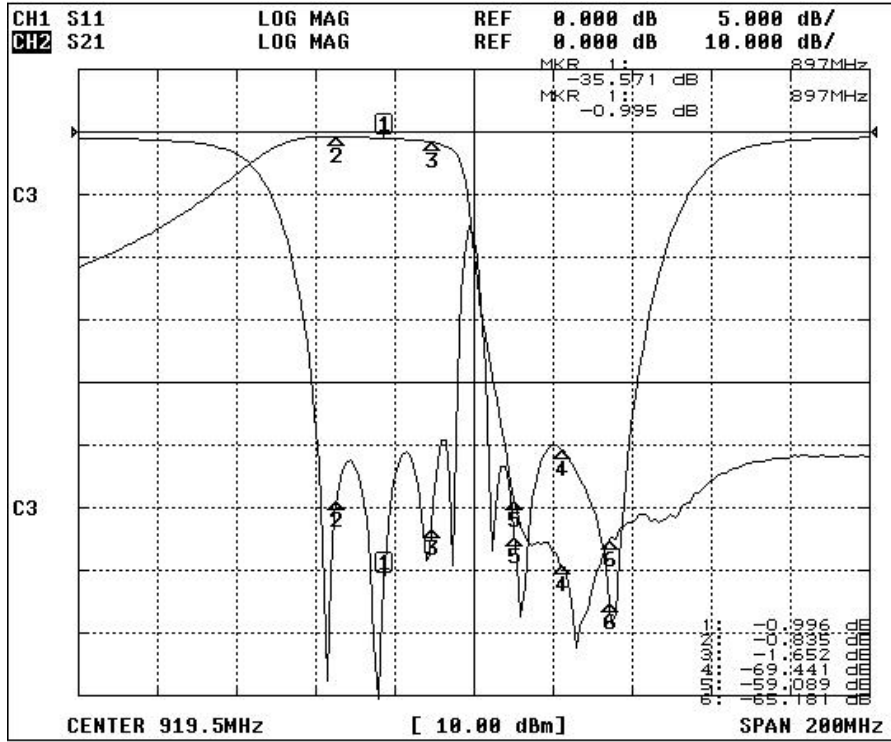
**Electrical Specification**

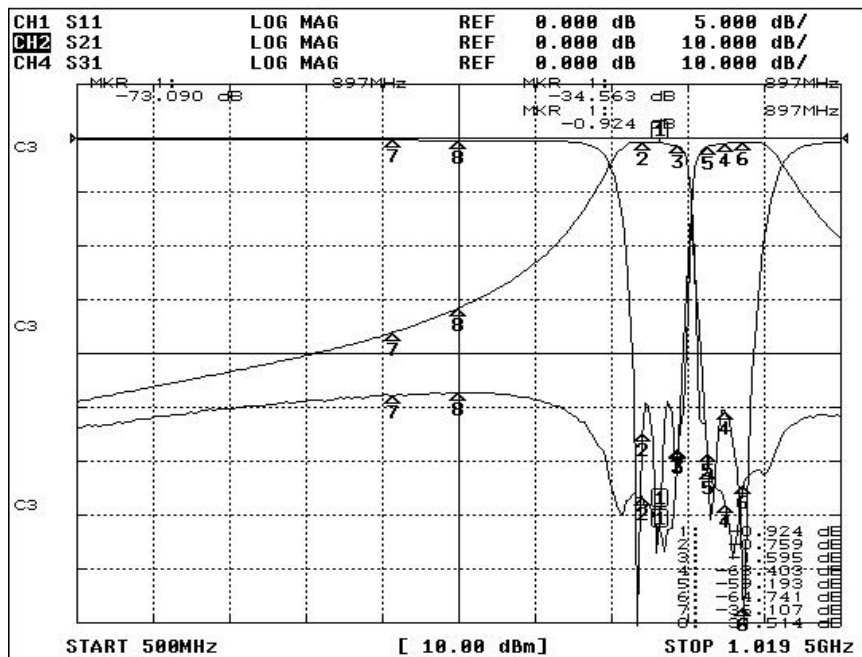
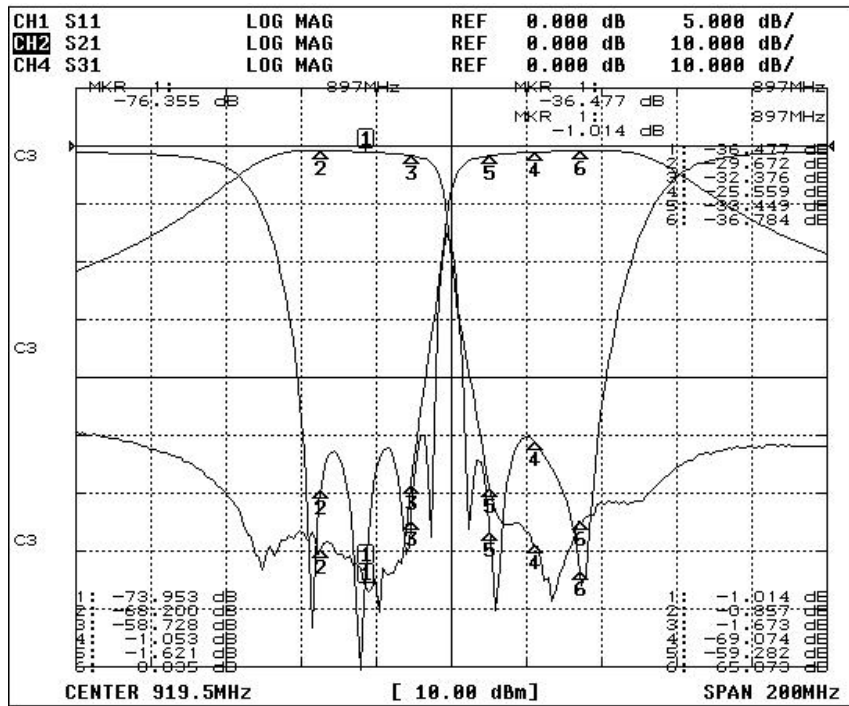
ITEMS	ANT >> Low	ANT >> High	UNIT
Center Frequency [fo]	897.0	942.0	MHz
Bandwidth [BW]	fo ±12.0	fo ±12.0	MHz
Insertion Loss in BW	2.3	2.0	dB max
Ripple in BW	1.2	1.0	dB max
Return Loss in BW			dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	35.0 dB min. @ DC-715	35.0 dB min. @ DC-760	MHz
	55.0 dB min. @ [ 930-954 ]	55.0 dB min. @ [ 885-909 ]	MHz
	dBmin. @ [ ~ ]	dB min. @ [ ~ ]	MHz
	dBmin. @ [ ~ ]	dB min. @ [ ~ ]	MHz
Group Delay Variation			ns max
Input Power	3.0		W max.
In/Out Impedance	50 Ω		
Operation Temperature Range	-40°C to +85°C		

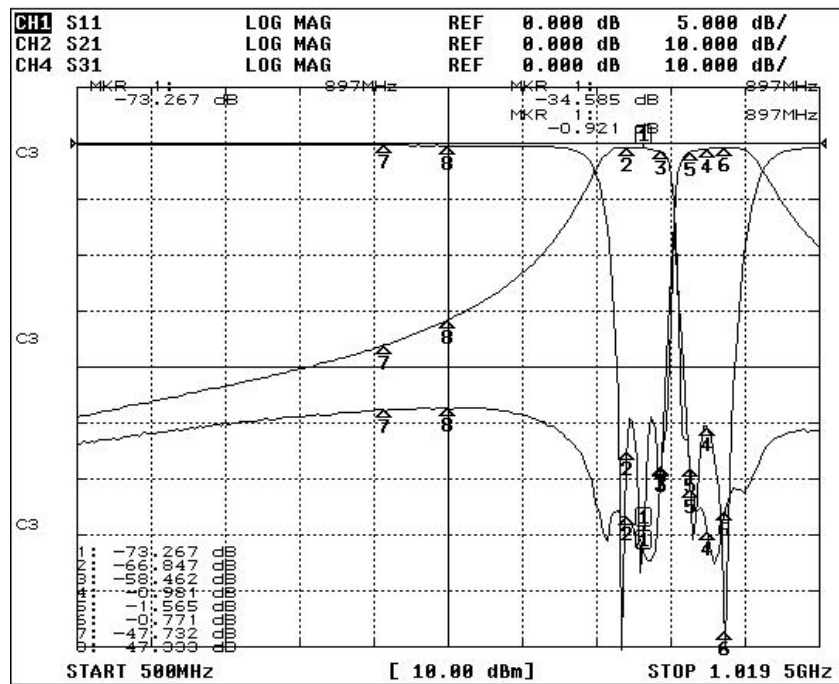
**Mechanical Specification**



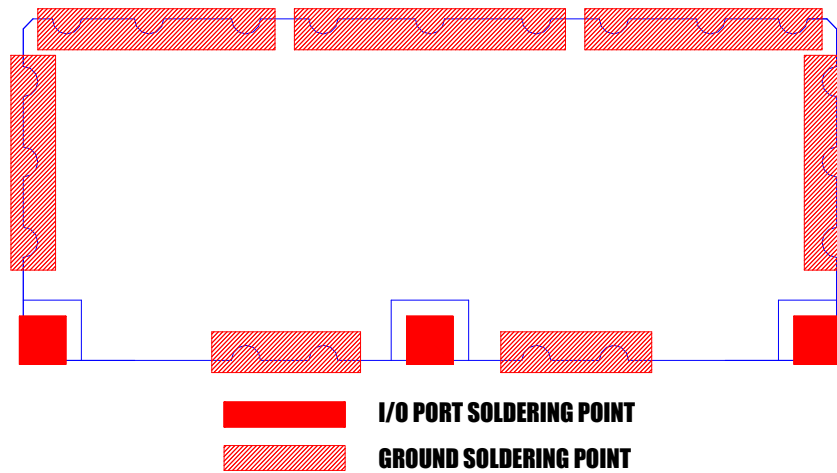
Plot Data



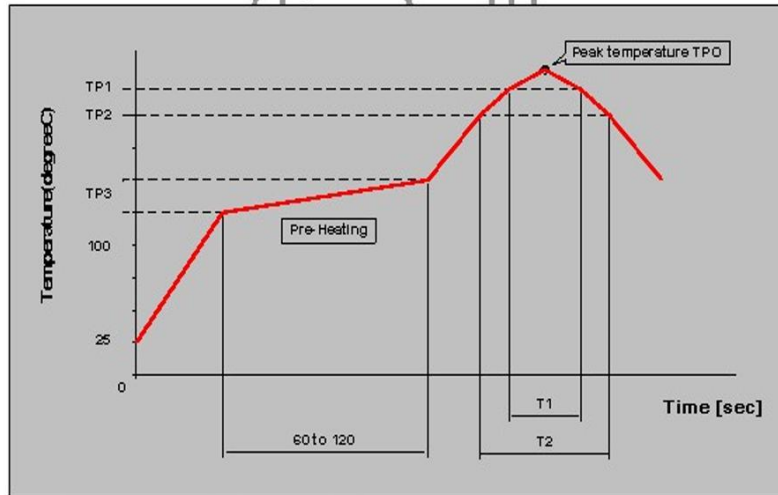




 Recommended PC Board Pattern



**Soldering Condition**



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TP0 (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±/5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180